

# 1.5V Drive Nch MOSFET

## RUQ050N02

### ●Structure

Silicon N-channel MOSFET

### ●Features

- 1) Low On-resistance.
- 2) Space saving, small surface mount package (TSMT6).
- 3) 1.5V drive

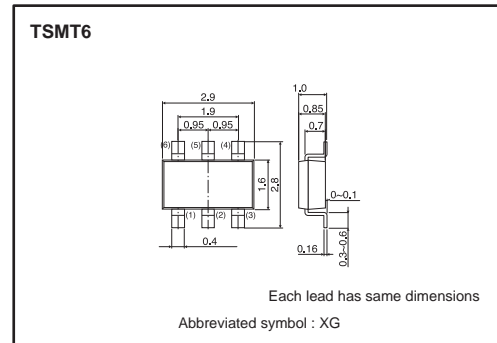
### ●Applications

Switching

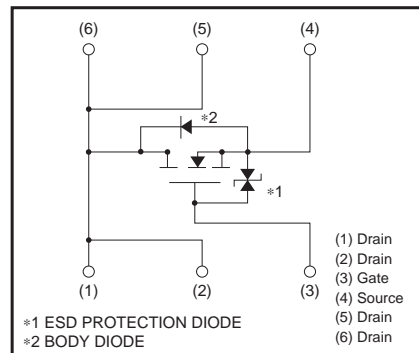
### ●Packaging specifications

| Type      | Package                      | Taping |
|-----------|------------------------------|--------|
|           | Code                         | TR     |
|           | Basic ordering unit (pieces) | 3000   |
| RUQ050N02 |                              | ○      |

### ●Dimensions (Unit : mm)



### ●Inner circuit



### ●Absolute maximum ratings (Ta=25°C)

| Parameter                    | Symbol     | Limits      | Unit      |   |
|------------------------------|------------|-------------|-----------|---|
| Drain-source voltage         | $V_{DSS}$  | 20          | V         |   |
| Gate-source voltage          | $V_{GSS}$  | $\pm 10$    | V         |   |
| Drain current                | Continuous | $I_D$       | $\pm 5.0$ | A |
|                              | Pulsed     | $I_{DP}$ *1 | $\pm 10$  | A |
| Source current (Body diode)  | Continuous | $I_S$       | 1.0       | A |
|                              | Pulsed     | $I_{SP}$ *1 | 10        | A |
| Total power dissipation      | $P_D$ *2   | 1.25        | W         |   |
| Channel temperature          | $T_{ch}$   | 150         | °C        |   |
| Range of storage temperature | $T_{stg}$  | -55 to +150 | °C        |   |

\*1  $P_w \leq 10\mu s$ , Duty cycle  $\leq 1\%$

\*2 Mounted on a ceramic board

### ●Thermal resistance

| Parameter          | Symbol           | Limits | Unit |
|--------------------|------------------|--------|------|
| Channel to ambient | $R_{th(ch-a)}$ * | 100    | °C/W |

\* Mounted on a ceramic board

**●Electrical characteristics (Ta=25°C)**

| Parameter                               | Symbol                  | Min. | Typ. | Max. | Unit | Conditions                                    |
|---|-------------------------|------|------|------|------|---|
| Gate-source leakage                     | I <sub>GSS</sub>        | –    | –    | ±10  | μA   | V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V    |
| Drain-source breakdown voltage          | V <sub>(BR) DSS</sub>   | 20   | –    | –    | V    | I <sub>D</sub> = 1mA, V <sub>GS</sub> =0V     |
| Zero gate voltage drain current         | I <sub>DSS</sub>        | –    | –    | 1    | μA   | V <sub>DS</sub> = 20V, V <sub>GS</sub> =0V    |
| Gate threshold voltage                  | V <sub>GS (th)</sub>    | 0.3  | –    | 1.0  | V    | V <sub>DS</sub> = 10V, I <sub>D</sub> = 1mA   |
| Static drain-source on-state resistance | R <sub>DSS (on)</sub> * | –    | 22   | 30   | mΩ   | I <sub>D</sub> = 5.0A, V <sub>GS</sub> = 4.5V |
|   |                         | –    | 27   | 38   | mΩ   | I <sub>D</sub> = 5.0A, V <sub>GS</sub> = 2.5V |
|   |                         | –    | 32   | 45   | mΩ   | I <sub>D</sub> = 2.5A, V <sub>GS</sub> = 1.8V |
|   |                         | –    | 40   | 80   | mΩ   | I <sub>D</sub> = 1.0A, V <sub>GS</sub> = 1.5V |
| Forward transfer admittance             | Y <sub>fs</sub>   *     | 6.5  | –    | –    | S    | V <sub>DS</sub> = 10V, I <sub>D</sub> = 5.0A  |
| Input capacitance                       | C <sub>iss</sub>        | –    | 900  | –    | pF   | V <sub>DS</sub> = 10V                         |
| Output capacitance                      | C <sub>oss</sub>        | –    | 190  | –    | pF   | V <sub>GS</sub> =0V                           |
| Reverse transfer capacitance            | C <sub>rss</sub>        | –    | 120  | –    | pF   | f=1MHz  |
| Turn-on delay time                      | t <sub>d (on)</sub> *   | –    | 15   | –    | ns   | V <sub>DD</sub> ≐ 10V                         |
| Rise time                               | t <sub>r</sub> *        | –    | 25   | –    | ns   | I <sub>D</sub> = 2.5A                         |
| Turn-off delay time                     | t <sub>d (off)</sub> *  | –    | 70   | –    | ns   | V <sub>GS</sub> = 4.5V                        |
| Fall time                               | t <sub>f</sub> *        | –    | 100  | –    | ns   | R <sub>L</sub> ≐ 4Ω                           |
| Total gate charge                       | Q <sub>g</sub> *        | –    | 12   | –    | nC   | V <sub>DD</sub> ≐ 10V, I <sub>D</sub> = 5.0A  |
| Gate-source charge                      | Q <sub>gs</sub> *       | –    | 2.5  | –    | nC   | V <sub>GS</sub> = 4.5V                        |
| Gate-drain charge                       | Q <sub>gd</sub> *       | –    | 1.7  | –    | nC   | R <sub>L</sub> ≐ 2Ω, R <sub>G</sub> =10Ω      |

\*Pulsed

**●Body diode characteristics (Source-drain) (Ta=25°C)**

| Parameter       | Symbol            | Min. | Typ. | Max. | Unit | Conditions                                 |
|-----------------|-------------------|------|------|------|------|--|
| Forward voltage | V <sub>SD</sub> * | –    | –    | 1.2  | V    | I <sub>S</sub> = 1.0A, V <sub>GS</sub> =0V |

\*Pulsed

●Electrical characteristics curves

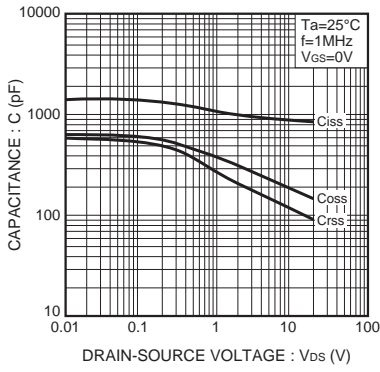


Fig.1 Typical Capacitance vs. Drain-Source Voltage

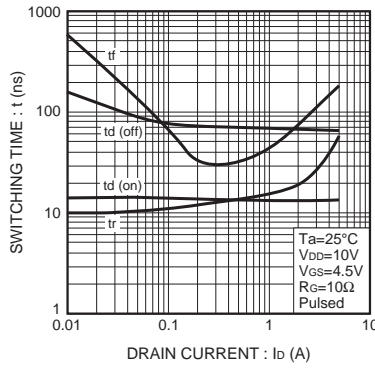


Fig.2 Switching Characteristics

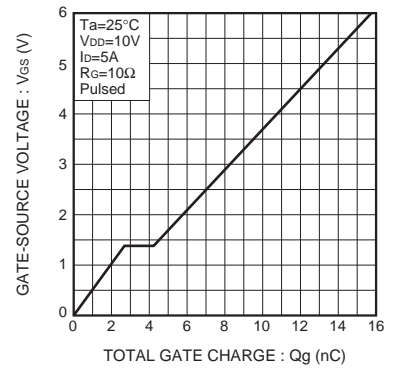


Fig.3 Dynamic Input Characteristics

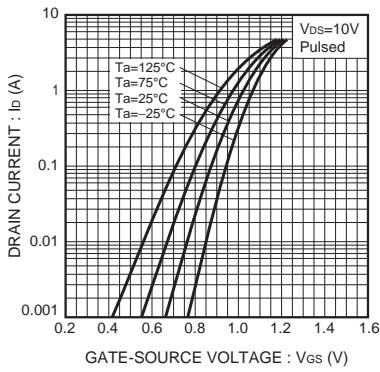


Fig.4 Typical Transfer Characteristics

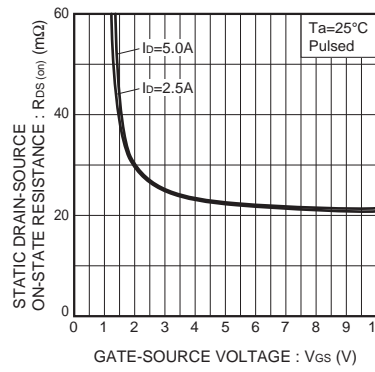


Fig.5 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

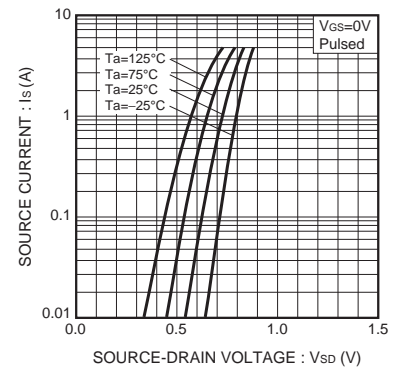


Fig.6 Source Current vs. Source-Drain Voltage

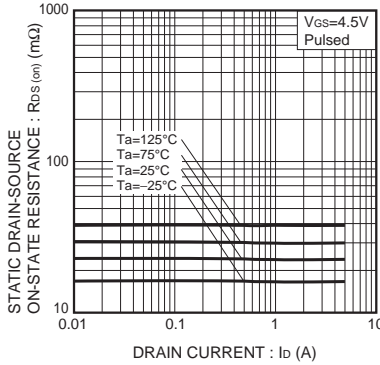


Fig.7 Static Drain-Source On-State Resistance vs. Drain current (I)

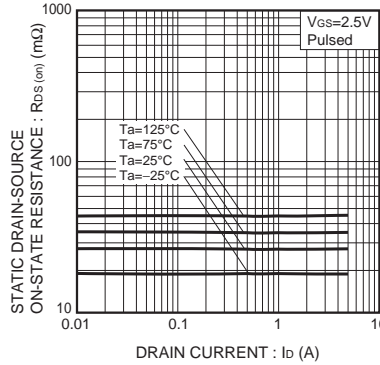


Fig.8 Static Drain-Source On-State Resistance vs. Drain current (II)

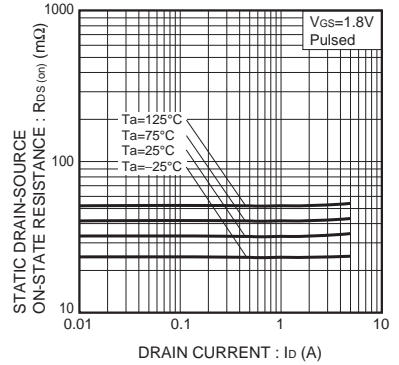


Fig.9 Static Drain-Source On-State Resistance vs. Drain current (III)

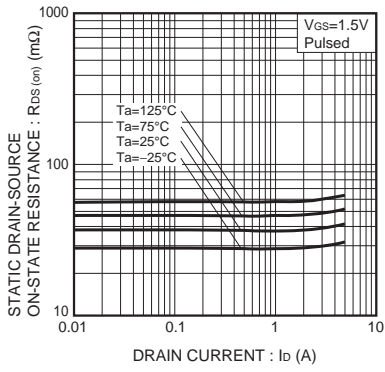


Fig.10 Static Drain-Source On-State Resistance vs. Drain current (IV)

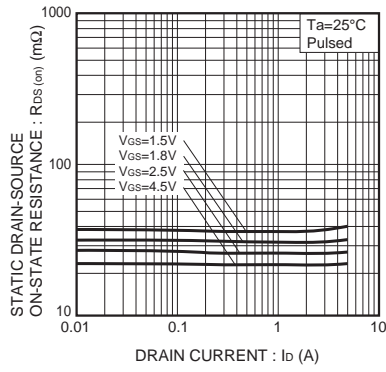


Fig.11 Static Drain-Source On-State Resistance vs. Drain current (IV)

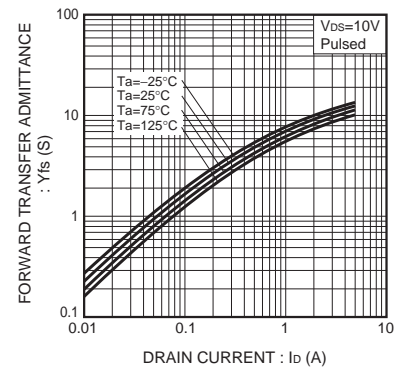


Fig.12 Forward Transfer Admittance vs. Drain current

●Measurement circuit

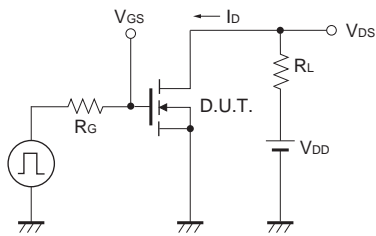


Fig.13 Switching Time Measurement Circuit

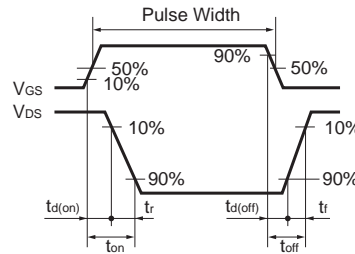


Fig.14 Switching Waveforms

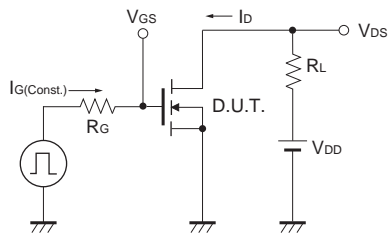


Fig.15 Gate Charge Measurement Circuit

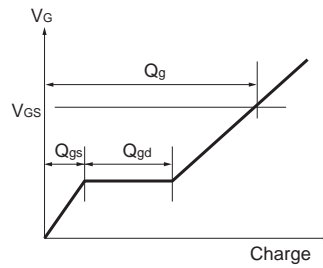


Fig.16 Gate Charge Waveform

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